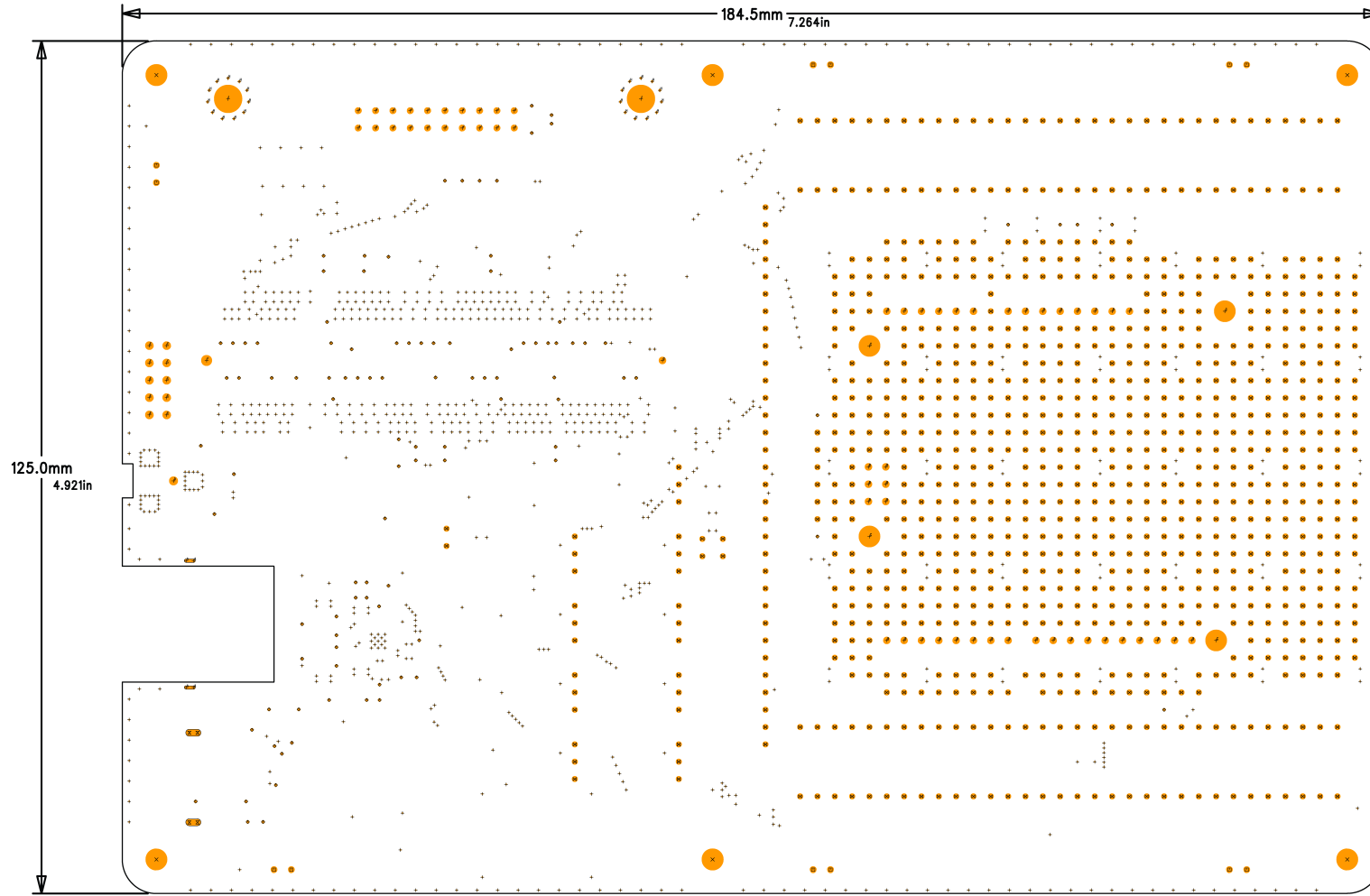


LAYERS: 4 (1oz/0.5oz/0.5oz/1oz)
MATERIAL: FR4, RoHS, 94v0
THICKNESS: 1.6mm (62.99 mils)
MINIMUM SPACING: 0.1524 mm (6 mils)
MINIMUM TRACE: 0.1524 mm (6 mils)
SMALLEST VIA: 0.254 mm drill in 0.508 mm pad
(10 mil drill in 20 mil pad)
FINISH: Gold (ENIG)
SILK SCREEN: White
SOLDER MASK: Green

>> IMPORTANT FABRICATION NOTES <<

- 1) Many pads have intentional undersize solder mask openings/oversize pads for physical strength.
- 2) Make top and bottom solder masks exactly as shown. Do _NOT_ "open-up" the solder mask layers.
- 3) Some jumpers are intentionally closed with oversize solder paste. Do not remove any solder paste mask features.



SIZE	QTY	SYM	PLATED	TOL
10	938	+	YES	+/-0.0
125.98	6	×	YES	+/-0.0
39.37	12	□	YES	+/-0.0
20	104	◇	YES	+/-0.0
39.37 x 86.61	2	⊗	YES	+/-0.0
35	879	⊗	YES	+/-0.0
19.69 x 62.99	2	⊕ ^A	YES	+/-0.0
43.31	38	⊕ ^B	YES	+/-0.0
125	4	⊕ ^C	YES	+/-0.0
51.18	1	⊕ ^D	YES	+/-0.0
49.21	10	⊕ ^E	YES	+/-0.0
62.99	1	⊕ ^F	YES	+/-0.0
43.31	1	⊕ ^G	YES	+/-0.0
15.75	22	⊕ ^H	YES	+/-0.0
163.39	2	⊕ ^I	YES	+/-0.0
39.37	20	⊕ ^J	YES	+/-0.0

BARE TRACE BEYOND EDGE IS INTENTIONAL
ESD HANDLING FEATURE. ROUTING WILL
TRIM COPPER TO EXACT BOARD OUTLINE.
SEE PDF "BOARD PREVIEW" FOR EXAMPLE.

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PROJECT **CFA-10037**

REVISION **1.0** DATE **2013 - 01 - 21**

LAYER
DRILL DRAWING

FILE NAME
C-10037_v1p0_DD.pho

CFA-10036: freescale i.MX28 ARM9 200-pin SODIMM Module

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PCB-10037 ver 1.0

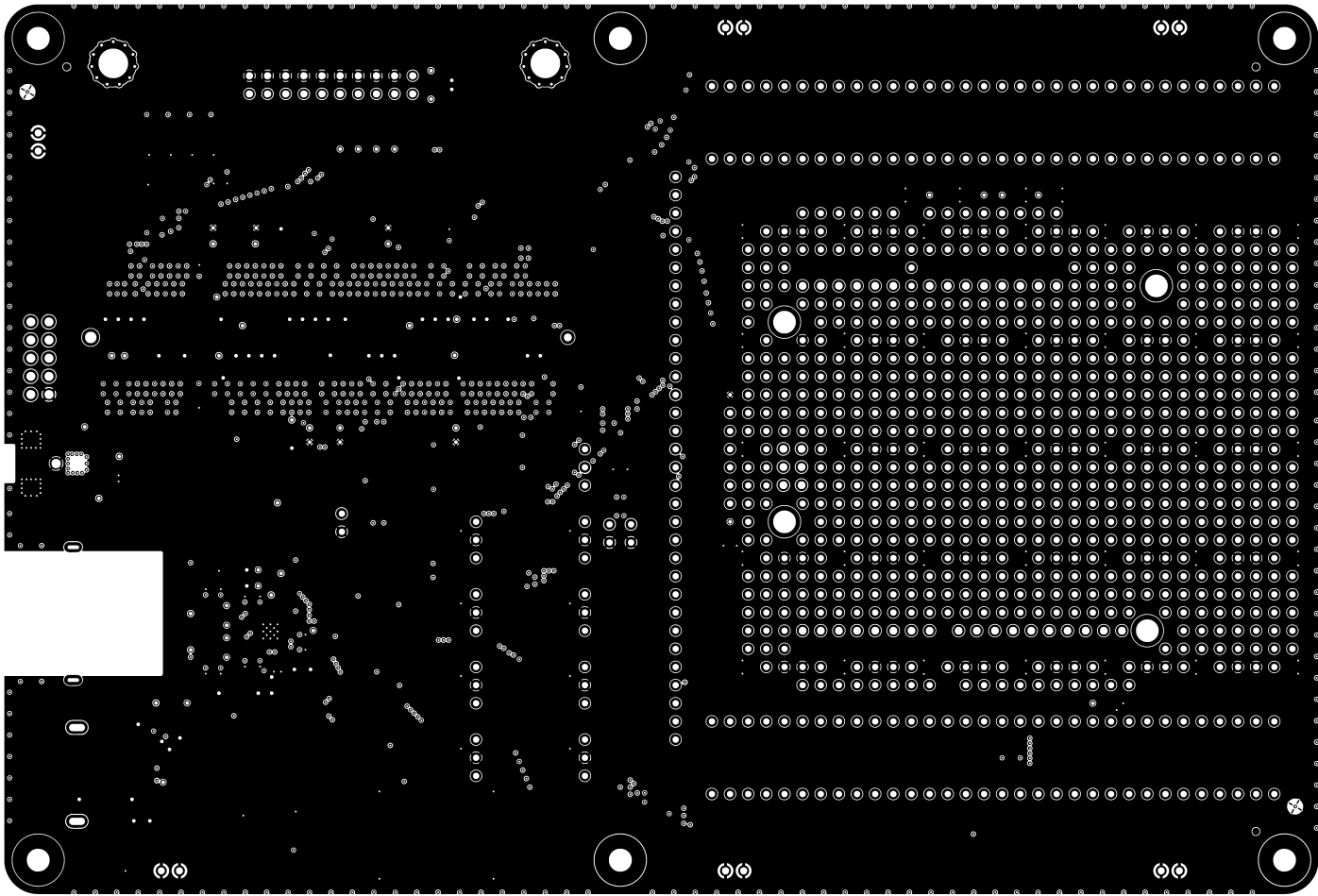
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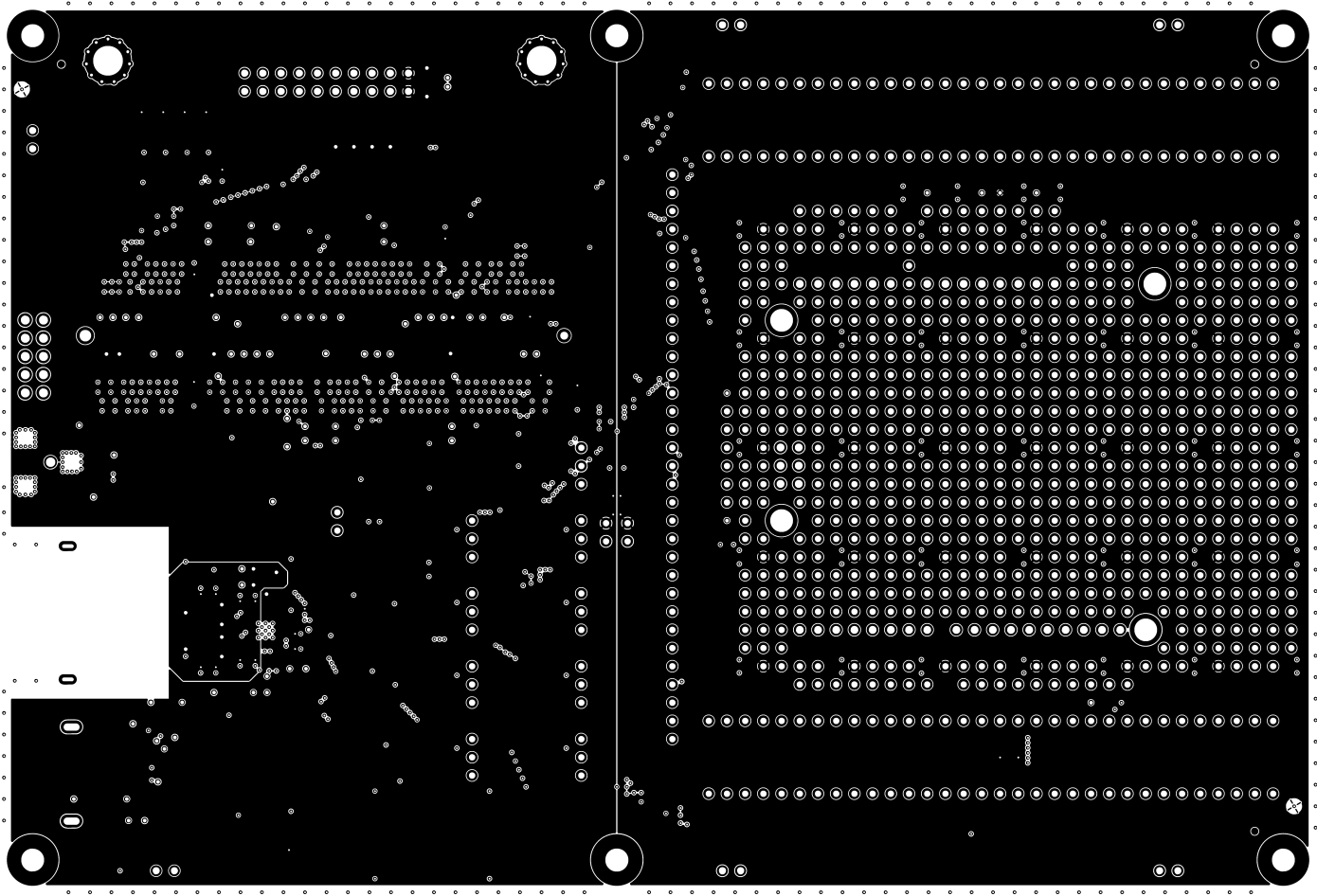
CFA-10036: freescale i.MX28 ARM9 200-pin SODIMM Module

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Model Label







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